## RRT-3UVPX-NVMe-R-C

# **3U VPX Conduction Cooled Carrier** with Removable NVMe SSD Module

The 3U VPX Conduction Cooled carrier with removable NVMe SSD module is for applications that require the frequent removal of SSD, fast transfer rates and large capacities. It consists of two components; the 3U VPX carrier board with PCI express (PCIe) interface to VPX backplane that mounts in one slot of 3U VPX chassis and the removable NVMe SSD module. The connectors between the drive module and the carrier are rated for 100,000 mating cycles to support frequent insertions and removals.

The NVMe SSD module can use any COTS U.2 NVMe Solid State Drive (SSD) providing capacities up to 16TB and transfer rates of up to 3940 MB/S. Options for TCG opal and military erase



### **FEATURES**

- Capacities up to 16 TB
- 3940 MB/S Transfer rates
- Removable SSD module
- PCIe Gen 3 x 4 interface
- 100,000 mating cycles
- OpenVPX Fat Pipe (FP)
   MOD-3-PER-1F-16.3.2.1 or 2
- VITA 46, 47, 48, 65
- Boot and/or storage disk
- Conduction cooled
- COTS U.2 NVMe SSDs
- Military erase options
- FIPS197,TCG Opal options
- Rugged design
- VxWorks™, Linux and Windows™ support



### EASILY REMOVE SSD DRIVE MODULE FROM VPX BOARD









# 3U VPX Conduction Cooled Carrier with PCIe Interface RRT-3UVPX-NVMe-R-A100-

OPTIONS (MAY BE LEFT BLANK)					
CONFORMAL COATING					
UR	POLYURETHANE				
AR	ACRYLIC				
EXTENDED TEMP. RANGE					
Х	-40° C to 85° C				

EXAMPLES: RRT-3UVPX-NVMe-R-C-UR-X RRT-3UVPX-NVMe-R-C

Removable NVMe	<u>e S</u>	<u>SD I</u>	<u>Driv</u>	<u>е Мо</u>	<u>odul</u>	3
RRT-DM-NVME-R-	٦-٢	<b>□-</b> [		7-[	7-	

REQUIREMENTS						
NAND FLASH TYPE						
pSLC	PSUEDO SINGLE LEVEL CELL					
MLC	MULTI LEVEL CELL					
TLC	TRI LEVEL CELL (3D)					
CAPACITY						
CAPACITIES UP TO 16 TB						
OPTIONS (MAY BE LEFT BLANK)						
	CONFORMAL COATING					
UR	POLYURETHANE					
AR	ACRYLIC					
	EXTENDED TEMP. RANGE					
Х	-40° C to 85° C					
	NO TOOLS					
TS	THUMB SCREWS					
SECURITY						
FE	FAST ERASE					
SE1	NSA/CSS MANUAL 9-12 ERASE					
SE2	RCC-TG IRIG 106-107 CHAPTER 10 ERASE					
OPAL	TCG OPAL COMPLIANT					
FIPS197	FIPS197 COMPLIANT					

### **EXAMPLES**:

RRT-DM-NVMe-TLC-16TB RRT-DM-NVMe-pSLC-1TB-UR-X-SE1 RRT-DM-NVMe-MLC-8TB-UR-X



### 3U VPX Air Conduction Carrier with Removable NVMe SSD Module

PERFORMANCE								
NAND FLASH TYPE	TLC	MLC-X pSLC-X						
CAPACITIES <sup>1</sup>	UP TO 16TB	UP TO 8TB	UP TO 4TB					
INTERFACE <sup>2</sup>	PCIe GEN 3 X 4	PCIe GEN 2 x 4	PCIe GEN 2 x 4					
THROUGHPUT	3940 MB/S	800 MB/S	1000 MB/S					
RELIABILITY								
MTBF-DRIVE	1 MILLION HOURS	1 MILLION HOURS	2 MILLION HOURS					
MTBF-VPX BOARD <sup>6</sup>	3 MILLION HOURS	3 MILLION HOURS 3 MILLION HOURS						
DATA RETENTION	1 YEAR	1 YEAR	5 YEARS					
ENDURANCE (100GB) TOTAL BYTES WRITTEN	70TBW	70 TBW	250TBW					
ENDURANCE RATING <sup>7</sup>	5 YEARS							
CARRIER/DRIVE MODULE MATING CYCLES	100,000 CYCLES							
		POWER						
VOLTAGE	12V +/- 5%, +5V +/- 5%, +3.3	BV +/- 5%						
WATTS (IDLE)	7 W	1.5 W	1.5 W					
WATTS (ACTIVE)	20 W	10 W	10 W					
	ENV	IRONMENTAL						
OPERATING TEMP., VITA 47 CLASS <sup>3</sup>	0 to 60C, CC1	-40 to 85C, CC4	0 TO 60C, CC1 -40 to 85C, CC4					
STORAGE TEMP.	-40°C to 85°C	-40°C to 85°C	-40°C to 85°C					
ALTITUDE	80,000 FT (24,000 MTRS)	80,000 FT (24,000 MTRS)	80,000 FT (24,000 MTRS)					
RELATIVE HUMIDITY	5% TO 95%	5% TO 95%	5% TO 95%					
SHOCK, VITA 47 CLASS <sup>4</sup>	40 g 11 MILLISECOND HALF-SINE, OS2	40 g 11 MILLISECOND HALF-SINE, OS2	40 g 11 MILLISECOND HALF-SINE, OS2					
VIBRATION, VITA 47 CLASS <sup>5</sup>	0.1 g <sup>2</sup> /HZ100 HZ TO 1000 HZ, V3	0.1 g <sup>2</sup> /HZ100 HZ TO 1000 HZ, V3	0.1 g <sup>2</sup> /HZ100 HZ TO 1000 HZ, V3					
		PHYSICAL						
FORM FACTOR	3U VPX							
WEIGHT	14 OZ MAX							
PITCH	0.8"							
		NOTES						

#### NOTES

- (1)Larger capacities available as new COTS U.2 NVMe drives released
- (2) Interface connected via compatible slot profile MOD-3-PER-1T-16.3.3.1 or 2
- (3) Thermal qualification per MIL-STD-810F, Method 501 Procedure II, and MIL-STD-810F, Method 502, Procedure II
- (4) Shock qualification per MIL-STD-810F, Method 516, Procedure I
- (5) Vibration qualification per MIL-STD-810F, Method 514, Procedure I
- (6) Telcordia SR-332, issue 3, operating temp (40C), electrical stress (50%), environmental factor (1.0)
- (7) Based on JESD218 standard with 4KB random write workload

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